

REMARKS/ARGUMENTS

The specification has been amended at page 18, line 25, changing "Comparative Examples 1 to 15" to "Comparative Examples 1 to 11".

Table 2 of the specification has been amended to delete original Comparative Examples 2, 3, 7 and 9 and the examples are renumbered. A clean copy and marked up copy are enclosed.

New Claim 9 has been added based on the proportions of components C, E and F disclosed on page 4, lines 16-17, page 7, line 9; and page 14, line 22, respectively.

Examination on the merits is awaited.

Respectfully submitted,

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TABLE 2

		Comparative Example														
		1	2	3	[4] 2	[5] 3	[6] 4	[7]	[8] 5	9	[10] 6	[11] 7	[12] 8	[13] 9	[14] 10	[15] 11
Phenol biphenylaralkyl type epoxy resin		7.4	3.6	9.6	9.4		7.4	7.4	7.5	7.442	7.6	7.35	7.35	7.4	7.35	7.35
	Biphenyl type epoxy resin		0.9													
	Cresol novolac type epoxy resin					6.9										
Phenol biphenylaralkyl resin		5.5	2.3	6.35			5.5	5.25	5.52	5.48	5.85	5.5	5.5	5.5	5.5	5.5
Phenol aralkyl resin			4.0			6.0										
Phenol novolac resin					3.5											
Spherical fused silica		86.0	84.0	83.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0	86.0
γ-Glycidylprmpyltrimethoxysilane		0.4	0.5	0.3	0.4	0.4		0.4	0.4	0.4		0.4	0.4	0.4	0.4	0.4
7-Me rcapto pro pyltrimethoxysilane							0.4									
Triphenylphosphine		0.2	0.43	0.25	0.15	0.15	0.2	0.2	0.06	0.2	0.2	0.2	0.2			
DBU														0.2		
Curing accelerator of formula C7)															0.25	
Curing accelerator of formula C8)																0.25
2,3-Dihydroxynaphthalens			0.07	0.4	0.05	0.05		0.55		0.008	0.05					
1,2-Dihydroxynaphthale ne																
Catechol																
Pyrogallo l																
1,6-Dihydroxynaphthalene												0.05				
Resorcinol													0.05			
Carnauba wax		0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2	0.2
Carbon black		0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3	0.3
Spiral flow (cm)		80	63	426	76	71	62	44B	114	84	76	78	81	68	89	77
Curing torque ratio (%)		65	62	66	67	70	62	22	7	65	56	65	64	57	85	89
Solder resistance-cracking	Chip delamination	4	chip exposure	0	2	chip exposure	3			4	9	5	4	4	2	3
Internal crack		0	V-O	V-1	V-1	HB	V-O	Poor releasing	Poor releasing	V-O	V-O	V-O	V-O	V-O	V-O	V-O
Fire retardancy		V-O	V-O	V-1	V-1	HB	V-O			V-O	V-O	V-O	V-O	V-O	V-O	V-O